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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are Embedded - System On Chip (SoC)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

Details

Product Status	Active
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	64KB
Peripherals	DMA, POR, WDT
Connectivity	CANbus, EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	800MHz
Primary Attributes	FPGA - 110K Logic Elements
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	896-BGA
Supplier Device Package	896-FBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5cstfd6d5f31i7n



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Symbol	Description	Condition	Minimum ⁽¹¹⁾	Typical	Maximum ⁽¹¹⁾	Unit
		1.8 V	1.71	1.8	1.89	V
V _{CCPLL_HPS}	HPS PLL analog voltage regulator power supply	—	2.375	2.5	2.625	V
V _{CC_AUX_SHARED} ⁽¹⁴⁾	HPS auxiliary power supply	—	2.375	2.5	2.625	V

Related Information

[Recommended Operating Conditions](#) on page 8

Provides the steady-state voltage values for the FPGA portion of the device.

DC Characteristics

Supply Current and Power Consumption

Intel offers two ways to estimate power for your design—the Excel-based EPE and the Intel® Quartus® Prime Power Analyzer feature.

Use the Excel-based EPE before you start your design to estimate the supply current for your design. The EPE provides a magnitude estimate of the device power because these currents vary greatly with the resources you use.

The Intel Quartus Prime Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

Related Information

- [Early Power Estimator User Guide](#)
Provides more information about power estimation tools.
- [Power Analysis chapter, Intel Quartus Prime Handbook](#)
Provides more information about power estimation tools.

⁽¹¹⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

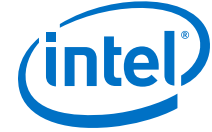
⁽¹⁴⁾ V_{CC_AUX_SHARED} must be powered by the same source as V_{CC_AUX} for Cyclone V SX C5, C6, D5, and D6 devices, and Cyclone V SE A5 and A6 devices.



Table 9. OCT Calibration Accuracy Specifications for Cyclone V Devices

Calibration accuracy for the calibrated on-chip series termination (R_S OCT) and on-chip parallel termination (R_T OCT) are applicable at the moment of calibration. When process, voltage, and temperature (PVT) conditions change after calibration, the tolerance may change.

Symbol	Description	Condition (V)	Calibration Accuracy			Unit
			-C6	-I7, -C7	-C8, -A7	
25- Ω R_S	Internal series termination with calibration (25- Ω setting)	$V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2$	± 15	± 15	± 15	%
50- Ω R_S	Internal series termination with calibration (50- Ω setting)	$V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2$	± 15	± 15	± 15	%
34- Ω and 40- Ω R_S	Internal series termination with calibration (34- Ω and 40- Ω setting)	$V_{CCIO} = 1.5, 1.35, 1.25, 1.2$	± 15	± 15	± 15	%
48- Ω , 60- Ω , and 80- Ω R_S	Internal series termination with calibration (48- Ω , 60- Ω , and 80- Ω setting)	$V_{CCIO} = 1.2$	± 15	± 15	± 15	%
50- Ω R_T	Internal parallel termination with calibration (50- Ω setting)	$V_{CCIO} = 2.5, 1.8, 1.5, 1.2$	-10 to +40	-10 to +40	-10 to +40	%
20- Ω , 30- Ω , 40- Ω , 60- Ω , and 120- Ω R_T	Internal parallel termination with calibration (20- Ω , 30- Ω , 40- Ω , 60- Ω , and 120- Ω setting)	$V_{CCIO} = 1.5, 1.35, 1.25$	-10 to +40	-10 to +40	-10 to +40	%
60- Ω and 120- Ω R_T	Internal parallel termination with calibration (60- Ω and 120- Ω setting)	$V_{CCIO} = 1.2$	-10 to +40	-10 to +40	-10 to +40	%
25- Ω $R_{S_left_shift}$	Internal left shift series termination with calibration (25- Ω $R_{S_left_shift}$ setting)	$V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2$	± 15	± 15	± 15	%



OCT Without Calibration Resistance Tolerance Specifications

Table 10. OCT Without Calibration Resistance Tolerance Specifications for Cyclone V Devices

This table lists the Cyclone V OCT without calibration resistance tolerance to PVT changes.

Symbol	Description	Condition (V)	Resistance Tolerance			Unit
			-C6	-I7, -C7	-C8, -A7	
25-Ω R _S	Internal series termination without calibration (25-Ω setting)	V _{CCIO} = 3.0, 2.5	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25-Ω setting)	V _{CCIO} = 1.8, 1.5	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25-Ω setting)	V _{CCIO} = 1.2	±35	±50	±50	%
50-Ω R _S	Internal series termination without calibration (50-Ω setting)	V _{CCIO} = 3.0, 2.5	±30	±40	±40	%
50-Ω R _S	Internal series termination without calibration (50-Ω setting)	V _{CCIO} = 1.8, 1.5	±30	±40	±40	%
50-Ω R _S	Internal series termination without calibration (50-Ω setting)	V _{CCIO} = 1.2	±35	±50	±50	%
100-Ω R _D	Internal differential termination (100-Ω setting)	V _{CCIO} = 2.5	±25	±40	±40	%

Figure 2. Equation for OCT Variation Without Recalibration

$$R_{OCT} = R_{SCAL} \left(1 + \left\langle \frac{dR}{dT} \times \Delta T \right\rangle \pm \left\langle \frac{dR}{dV} \times \Delta V \right\rangle \right)$$

The definitions for the equation are as follows:

- The R_{OCT} value calculated shows the range of OCT resistance with the variation of temperature and V_{CCIO}.
- R_{SCAL} is the OCT resistance value at power-up.
- ΔT is the variation of temperature with respect to the temperature at power up.



I/O Standard	V _{CCIO} (V)			V _{REF} (V)			V _{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-15 Class I, II	1.425	1.5	1.575	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
SSTL-135 Class I, II	1.283	1.35	1.418	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
SSTL-125 Class I, II	1.19	1.25	1.26	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	$V_{CCIO}/2$	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	$V_{CCIO}/2$	—
HSTL-12 Class I, II	1.14	1.2	1.26	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$	—	$V_{CCIO}/2$	—
HSUL-12	1.14	1.2	1.3	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	—	—	—

Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications

Table 17. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Cyclone V Devices

I/O Standard	V _{IL(DC)} (V)		V _{IH(DC)} (V)		V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{OL} (V)	V _{OH} (V)	I _{OL} ⁽¹⁹⁾ (mA)	I _{OH} ⁽¹⁹⁾ (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	V _{REF} - 0.15	V _{REF} + 0.15	V _{CCIO} + 0.3	V _{REF} - 0.31	V _{REF} + 0.31	V _{TT} - 0.608	V _{TT} + 0.608	8.1	-8.1
SSTL-2 Class II	-0.3	V _{REF} - 0.15	V _{REF} + 0.15	V _{CCIO} + 0.3	V _{REF} - 0.31	V _{REF} + 0.31	V _{TT} - 0.81	V _{TT} + 0.81	16.2	-16.2
SSTL-18 Class I	-0.3	V _{REF} - 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} - 0.25	V _{REF} + 0.25	V _{TT} - 0.603	V _{TT} + 0.603	6.7	-6.7
SSTL-18 Class II	-0.3	V _{REF} - 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} - 0.25	V _{REF} + 0.25	0.28	V _{CCIO} - 0.28	13.4	-13.4

continued...

⁽¹⁹⁾ To meet the I_{OL} and I_{OH} specifications, you must set the current strength settings accordingly. For example, to meet the SSTL15CI specification (8 mA), you should set the current strength settings to 8 mA. Setting at lower current strength may not meet the I_{OL} and I_{OH} specifications in the datasheet.



Symbol/Description	Condition	Transceiver Speed Grade 5 ⁽³⁰⁾			Transceiver Speed Grade 6			Transceiver Speed Grade 7			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Intra-differential pair skew	TX V_{CM} = 0.65 V and slew rate of 15 ps	—	—	15	—	—	15	—	—	15	ps
Intra-transceiver block transmitter channel-to-channel skew	×6 PMA bonded mode	—	—	180	—	—	180	—	—	180	ps
Inter-transceiver block transmitter channel-to-channel skew	×N PMA bonded mode	—	—	500	—	—	500	—	—	500	ps

Table 25. CMU PLL Specifications for Cyclone V GX, GT, SX, and ST Devices

Symbol/Description	Condition	Transceiver Speed Grade 5 ⁽³⁰⁾			Transceiver Speed Grade 6			Transceiver Speed Grade 7			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Supported data range	—	614	—	5000/6144 ⁽³⁵⁾	614	—	3125	614	—	2500	Mbps
fPLL supported data range	—	614	—	3125	614	—	3125	614	—	2500	Mbps

Table 26. Transceiver-FPGA Fabric Interface Specifications for Cyclone V GX, GT, SX, and ST Devices

Symbol/Description	Condition	Transceiver Speed Grade 5 ⁽³⁰⁾			Transceiver Speed Grade 6			Transceiver Speed Grade 7			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Interface speed (single-width mode)	—	25	—	187.5	25	—	187.5	25	—	163.84	MHz
Interface speed (double-width mode)	—	25	—	163.84	25	—	163.84	25	—	156.25	MHz

Related Information

- [CTLE Response at Data Rates > 3.25 Gbps across Supported AC Gain and DC Gain](#) on page 32
- [CTLE Response at Data Rates ≤ 3.25 Gbps across Supported AC Gain and DC Gain](#) on page 33
- [PCIe Supported Configurations and Placement Guidelines](#)
Provides more information about the maximum full duplex channels recommended in Cyclone V GT and ST devices which require full compliance to the PCIe Gen2 transmit jitter specification.



Typical TX V_{OD} Setting for Cyclone V Transceiver Channels with termination of 100 Ω

Table 27. Typical TX V_{OD} Setting for Cyclone V Transceiver Channels with termination of 100 Ω

Symbol	V_{OD} Setting ⁽⁴⁸⁾	V_{OD} Value (mV)	V_{OD} Setting ⁽⁴⁸⁾	V_{OD} Value (mV)
V_{OD} differential peak-to-peak typical	6 ⁽⁴⁹⁾	120	34	680
	7 ⁽⁴⁹⁾	140	35	700
	8 ⁽⁴⁹⁾	160	36	720
	9	180	37	740
	10	200	38	760
	11	220	39	780
	12	240	40	800
	13	260	41	820
	14	280	42	840
	15	300	43	860
	16	320	44	880
	17	340	45	900
	18	360	46	920
	19	380	47	940
	20	400	48	960
	21	420	49	980
	22	440	50	1000
23	460	51	1020	
24	480	52	1040	

continued...

⁽⁴⁸⁾ Convert these values to their binary equivalent form if you are using the dynamic reconfiguration mode for PMA analog controls.

⁽⁴⁹⁾ Only valid for data rates \leq 5 Gbps.



Exceptions for PCIe Gen2 design:

- V_{OD} setting = 50 and pre-emphasis setting = 22 are allowed for PCIe Gen2 design with transmit de-emphasis -6dB setting ($pipe_txdeemp = 1'b0$) using Intel PCIe Hard IP and PIPE IP cores.
- V_{OD} setting = 50 and pre-emphasis setting = 12 are allowed for PCIe Gen2 design with transmit de-emphasis -3.5dB setting ($pipe_txdeemp = 1'b1$) using Intel PCIe Hard IP and PIPE IP cores.

For example, when $V_{OD} = 800$ mV, the corresponding V_{OD} value setting is 40. The following conditions show that the 1st post tap pre-emphasis setting = 2 is valid:

- $|B| + |C| \leq 60 \rightarrow 40 + 2 = 42$
- $|B| - |C| > 5 \rightarrow 40 - 2 = 38$
- $(V_{MAX}/V_{MIN} - 1)\% < 600\% \rightarrow (42/38 - 1)\% = 10.52\%$

To predict the pre-emphasis level for your specific data rate and pattern, run simulations using the Cyclone V HSSI HSPICE models.

Table 28. Transmitter Pre-Emphasis Levels for Cyclone V Devices

Intel Quartus Prime 1st Post Tap Pre-Emphasis Setting	Intel Quartus Prime V_{OD} Setting							Unit
	10 (200 mV)	20 (400 mV)	30 (600 mV)	35 (700 mV)	40 (800 mV)	45 (900 mV)	50 (1000 mV)	
0	0	0	0	0	0	0	0	dB
1	1.97	0.88	0.43	0.32	0.24	0.19	0.13	dB
2	3.58	1.67	0.95	0.76	0.61	0.5	0.41	dB
3	5.35	2.48	1.49	1.2	1	0.83	0.69	dB
4	7.27	3.31	2	1.63	1.36	1.14	0.96	dB
5	—	4.19	2.55	2.1	1.76	1.49	1.26	dB
6	—	5.08	3.11	2.56	2.17	1.83	1.56	dB
7	—	5.99	3.71	3.06	2.58	2.18	1.87	dB
8	—	6.92	4.22	3.47	2.93	2.48	2.11	dB
9	—	7.92	4.86	4	3.38	2.87	2.46	dB
10	—	9.04	5.46	4.51	3.79	3.23	2.77	dB

continued...

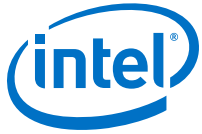


Intel Quartus Prime 1st Post Tap Pre-Emphasis Setting	Intel Quartus Prime V _{OD} Setting							Unit
	10 (200 mV)	20 (400 mV)	30 (600 mV)	35 (700 mV)	40 (800 mV)	45 (900 mV)	50 (1000 mV)	
11	—	10.2	6.09	5.01	4.23	3.61	—	dB
12	—	11.56	6.74	5.51	4.68	3.97	—	dB
13	—	12.9	7.44	6.1	5.12	4.36	—	dB
14	—	14.44	8.12	6.64	5.57	4.76	—	dB
15	—	—	8.87	7.21	6.06	5.14	—	dB
16	—	—	9.56	7.73	6.49	—	—	dB
17	—	—	10.43	8.39	7.02	—	—	dB
18	—	—	11.23	9.03	7.52	—	—	dB
19	—	—	12.18	9.7	8.02	—	—	dB
20	—	—	13.17	10.34	8.59	—	—	dB
21	—	—	14.2	11.1	—	—	—	dB
22	—	—	15.38	11.87	—	—	—	dB
23	—	—	—	12.67	—	—	—	dB
24	—	—	—	13.48	—	—	—	dB
25	—	—	—	14.37	—	—	—	dB
26	—	—	—	—	—	—	—	dB
27	—	—	—	—	—	—	—	dB
28	—	—	—	—	—	—	—	dB
29	—	—	—	—	—	—	—	dB
30	—	—	—	—	—	—	—	dB
31	—	—	—	—	—	—	—	dB

Related Information

[SPICE Models for Intel Devices](#)

Provides the Cyclone V HSSI HSPICE models.



Transceiver Compliance Specification

The following table lists the physical medium attachment (PMA) specification compliance of all supported protocol for Cyclone V GX, GT, SX, and ST devices. For more information about the protocol parameter details and compliance specifications, contact your Intel Sales Representative.

Table 29. Transceiver Compliance Specification for All Supported Protocol for Cyclone V GX, GT, SX, and ST Devices

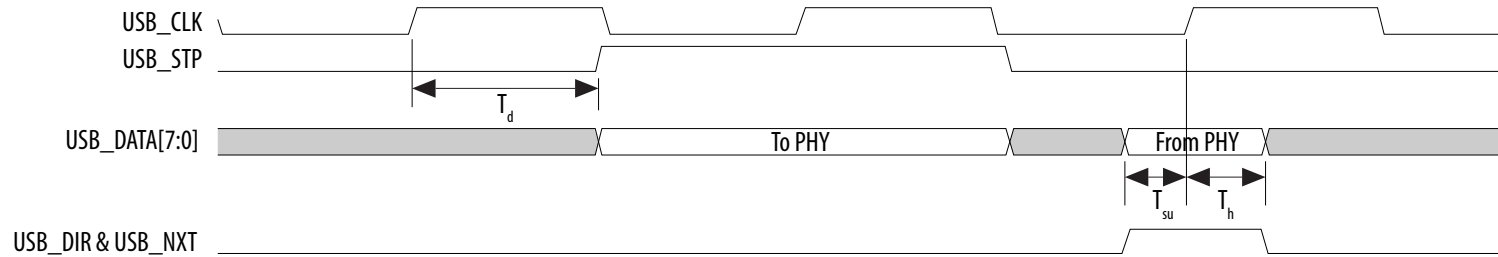
Protocol	Sub-protocol	Data Rate (Mbps)
PCIe	PCIe Gen1	2,500
	PCIe Gen2 ⁽⁵⁰⁾	5,000
	PCIe Cable	2,500
XAUI	XAUI 2135	3,125
Serial RapidIO® (SRIO)	SRIO 1250 SR	1,250
	SRIO 1250 LR	1,250
	SRIO 2500 SR	2,500
	SRIO 2500 LR	2,500
	SRIO 3125 SR	3,125
	SRIO 3125 LR	3,125
	SRIO 5000 SR	5,000
	SRIO 5000 MR	5,000
	SRIO 5000 LR	5,000
Common Public Radio Interface (CPRI)	CPRI E6LV	614.4
	CPRI E6HV	614.4
	CPRI E6LVII	614.4

continued...

⁽⁵⁰⁾ For PCIe Gen2 sub-protocol, Intel recommends increasing the V_{CCE_GXBL} and V_{CCL_GXBL} typical value from 1.1 V to 1.2 V for Cyclone V GT and ST FPGA systems which ensure full compliance to the PCIe Gen2 transmit jitter specification. For more information about the maximum full duplex channels recommended in Cyclone V GT and ST devices under this condition, refer to the *Transceiver Protocol Configurations in Cyclone V Devices* chapter.



Figure 10. USB Timing Diagram

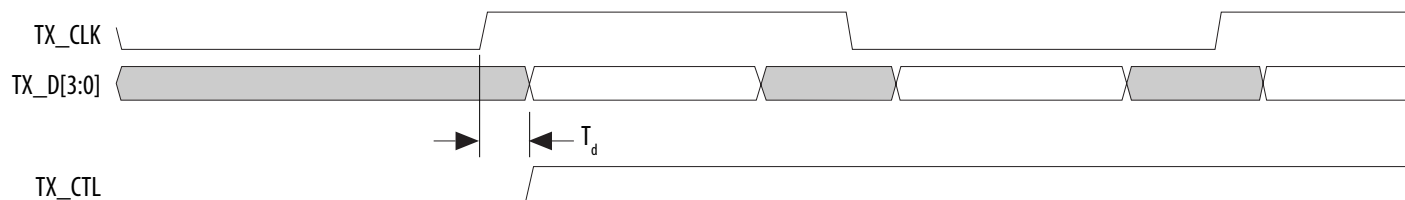


Ethernet Media Access Controller (EMAC) Timing Characteristics

Table 48. Reduced Gigabit Media Independent Interface (RGMII) TX Timing Requirements for Cyclone V Devices

Symbol	Description	Min	Typ	Max	Unit
T_{clk} (1000Base-T)	TX_CLK clock period	—	8	—	ns
T_{clk} (100Base-T)	TX_CLK clock period	—	40	—	ns
T_{clk} (10Base-T)	TX_CLK clock period	—	400	—	ns
T_{duty}	TX_CLK duty cycle	45	—	55	%
T_d	TX_CLK to TXD/TX_CTL output data delay	-0.85	—	0.15	ns

Figure 11. RGMII TX Timing Diagram





CAN Interface

The maximum controller area network (CAN) data rate is 1 Mbps.

HPS JTAG Timing Specifications

Table 54. HPS JTAG Timing Parameters and Values for Cyclone V Devices

Symbol	Description	Min	Max	Unit
t_{JCP}	TCK clock period	30	—	ns
t_{JCH}	TCK clock high time	14	—	ns
t_{JCL}	TCK clock low time	14	—	ns
$t_{JPSU (TDI)}$	TDI JTAG port setup time	2	—	ns
$t_{JPSU (TMS)}$	TMS JTAG port setup time	3	—	ns
t_{JPH}	JTAG port hold time	5	—	ns
t_{JPCO}	JTAG port clock to output	—	12 ⁽⁷³⁾	ns
t_{JPZX}	JTAG port high impedance to valid output	—	14 ⁽⁷³⁾	ns
t_{JPXZ}	JTAG port valid output to high impedance	—	14 ⁽⁷³⁾	ns

Configuration Specifications

This section provides configuration specifications and timing for Cyclone V devices.

⁽⁷³⁾ A 1-ns adder is required for each V_{CCIO_HPS} voltage step down from 3.0 V. For example, t_{JPCO} = 13 ns if V_{CCIO_HPS} of the TDO I/O bank = 2.5 V, or 14 ns if it equals 1.8 V.



Configuration Scheme	Encryption	Compression	DCLK-to-DATA[] Ratio (r)
	On	Off	2
	Off	On	4
	On	On	4

FPP Configuration Timing when DCLK-to-DATA[] = 1

When you enable decompression or the design security feature, the DCLK-to-DATA[] ratio varies for FPP ×8 and FPP ×16. For the respective DCLK-to-DATA[] ratio, refer to the DCLK-to-DATA[] Ratio for Cyclone V Devices table.

Table 58. FPP Timing Parameters When DCLK-to-DATA[] Ratio is 1 for Cyclone V Devices

Symbol	Parameter	Minimum	Maximum	Unit
t _{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t _{CFG}	nCONFIG low pulse width	2	—	μs
t _{STATUS}	nSTATUS low pulse width	268	1506 ⁽⁷⁷⁾	μs
t _{CF2ST1}	nCONFIG high to nSTATUS high	—	1506 ⁽⁷⁸⁾	μs
t _{CF2CK} ⁽⁷⁹⁾	nCONFIG high to first rising edge on DCLK	1506	—	μs
t _{ST2CK} ⁽⁷⁹⁾	nSTATUS high to first rising edge of DCLK	2	—	μs
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t _{CH}	DCLK high time	0.45 × 1/f _{MAX}	—	s

continued...

⁽⁷⁷⁾ You can obtain this value if you do not delay configuration by extending the nCONFIG or the nSTATUS low pulse width.

⁽⁷⁸⁾ You can obtain this value if you do not delay configuration by externally holding the nSTATUS low.

⁽⁷⁹⁾ If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.



Symbol	Parameter	Minimum	Maximum	Unit
t _{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t _{CLK}	DCLK period	$1/f_{MAX}$	—	s
f _{MAX}	DCLK frequency (FPP ×8/ ×16)	—	125	MHz
t _{CD2UM}	CONF_DONE high to user mode ⁽⁸⁰⁾	175	437	μs
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{CD2CU} + (T _{init} × CLKUSR period)	—	—
T _{init}	Number of clock cycles required for device initialization	8,576	—	Cycles

Related Information

- [FPP Configuration Timing](#)
Provides the FPP configuration timing waveforms.
- [DCLK-to-DATA\[\] Ratio \(r\) for FPP Configuration](#) on page 69

FPP Configuration Timing when DCLK-to-DATA[] > 1

Table 59. FPP Timing Parameters When DCLK-to-DATA[] Ratio is >1 for Cyclone V Devices

Use these timing parameters when you use the decompression and design security features.

Symbol	Parameter	Minimum	Maximum	Unit
t _{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t _{CFG}	nCONFIG low pulse width	2	—	μs
t _{STATUS}	nSTATUS low pulse width	268	1506 ⁽⁸¹⁾	μs
t _{CF2ST1}	nCONFIG high to nSTATUS high	—	1506 ⁽⁸²⁾	μs

continued...

⁽⁸⁰⁾ The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

⁽⁸¹⁾ This value can be obtained if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.



DCLK Frequency Specification in the AS Configuration Scheme

Table 61. DCLK Frequency Specification in the AS Configuration Scheme

This table lists the internal clock frequency specification for the AS configuration scheme. The DCLK frequency specification applies when you use the internal oscillator as the configuration clock source. The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Parameter	Minimum	Typical	Maximum	Unit
DCLK frequency in AS configuration scheme	5.3	7.9	12.5	MHz
	10.6	15.7	25.0	MHz
	21.3	31.4	50.0	MHz
	42.6	62.9	100.0	MHz

Passive Serial (PS) Configuration Timing

Table 62. PS Timing Parameters for Cyclone V Devices

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t_{CFG}	nCONFIG low pulse width	2	—	μ s
t_{STATUS}	nSTATUS low pulse width	268	1506 ⁽⁸⁹⁾	μ s
t_{CF2ST1}	nCONFIG high to nSTATUS high	—	1506 ⁽⁹⁰⁾	μ s
t_{CF2CK} ⁽⁹¹⁾	nCONFIG high to first rising edge on DCLK	1506	—	μ s
t_{ST2CK} ⁽⁹¹⁾	nSTATUS high to first rising edge of DCLK	2	—	μ s
t_{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns

continued...

⁽⁸⁹⁾ You can obtain this value if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

⁽⁹⁰⁾ You can obtain this value if you do not delay configuration by externally holding nSTATUS low.

⁽⁹¹⁾ If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.



Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis.

The Intel Quartus Prime Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

Related Information

[Cyclone V I/O Timing Spreadsheet](#)

Provides the Cyclone V Excel-based I/O timing spreadsheet.

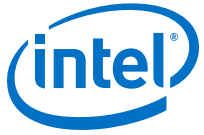
Programmable IOE Delay

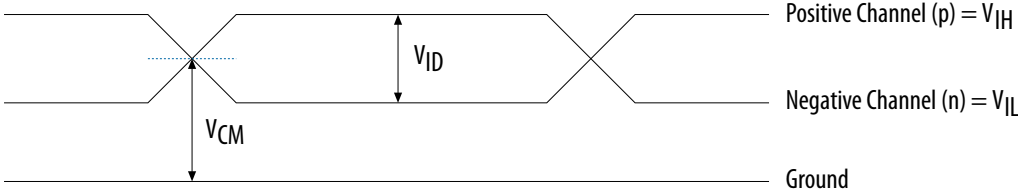
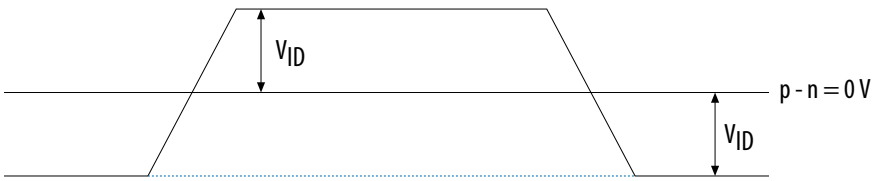
Table 68. I/O element (IOE) Programmable Delay for Cyclone V Devices

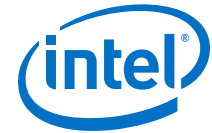
Parameter ⁽¹⁰⁰⁾	Available Settings	Minimum Offset ⁽¹⁰¹⁾	Fast Model		Slow Model					Unit
			Industrial	Commercial	-C6	-C7	-C8	-I7	-A7	
D1	32	0	0.508	0.517	0.971	1.187	1.194	1.179	1.160	ns
D3	8	0	1.761	1.793	3.291	4.022	3.961	3.999	3.929	ns
D4	32	0	0.510	0.519	1.180	1.187	1.195	1.180	1.160	ns
D5	32	0	0.508	0.517	0.970	1.186	1.194	1.179	1.179	ns

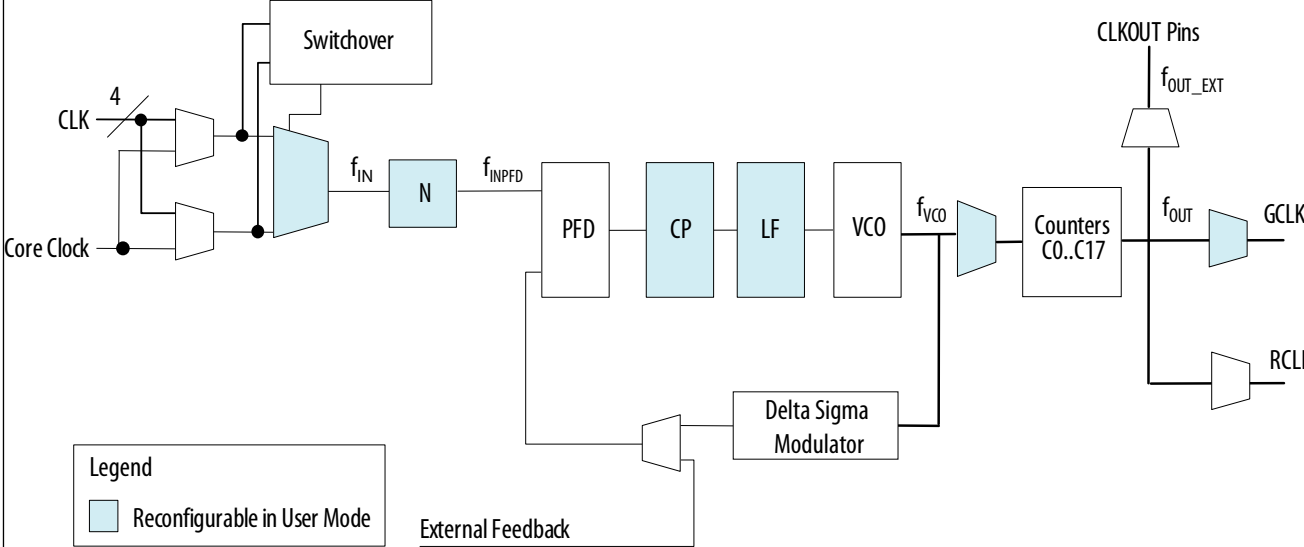
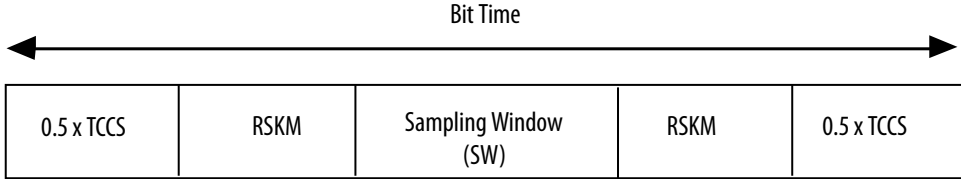
⁽¹⁰⁰⁾ You can set this value in the Intel Quartus Prime software by selecting **D1**, **D3**, **D4**, and **D5** in the **Assignment Name** column of **Assignment Editor**.

⁽¹⁰¹⁾ Minimum offset does not include the intrinsic delay.

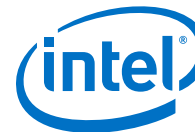


Term	Definition
	<p data-bbox="730 316 970 344">Single-Ended Waveform</p>  <p data-bbox="1507 365 1743 393">Positive Channel (p) = V_{IH}</p> <p data-bbox="1507 446 1743 474">Negative Channel (n) = V_{IL}</p> <p data-bbox="1507 527 1575 555">Ground</p> <p data-bbox="730 609 955 636">Differential Waveform</p>  <p data-bbox="1507 730 1596 758">$p - n = 0V$</p> <p data-bbox="592 860 886 888">Transmitter Output Waveforms</p> <p data-bbox="1738 917 1869 945"><i>continued...</i></p>



Term	Definition
	 <p>The diagram illustrates the PLL architecture. It starts with a 'Core Clock' input that branches into a '4' divider and a 'Switchover' block. The 'Switchover' block selects between the divided core clock and an external 'External Feedback' signal. The selected signal, labeled f_{IN}, passes through a divider 'N' to become f_{INPFD}. This signal then goes through a 'PFD' (Phase-Frequency Detector), a 'CP' (Charge Pump), a 'LF' (Loop Filter), and a 'VCO' (Voltage-Controlled Oscillator) to produce f_{VCO}. The f_{VCO} signal is then divided by a 'Counters CO..C17' block to produce f_{OUT}. This output is available at 'CLKOUT Pins' as f_{OUT_EXT} and also passes through a divider to become 'RCLK'. A 'Delta Sigma Modulator' is connected to the feedback path between the PFD and the VCO.</p> <p>Legend Reconfigurable in User Mode</p> <p>Note: (1) Core Clock can only be fed by dedicated clock input pins or PLL outputs.</p>
R_L	Receiver differential input discrete resistor (external to the Cyclone V device).
Sampling window (SW)	<p>Timing diagram—The period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position in the sampling window, as shown:</p>  <p>The timing diagram shows a horizontal axis labeled 'Bit Time'. A double-headed arrow spans the width of the diagram. Below the axis, a sequence of five rectangular blocks is shown: '0.5 x TCCS', 'RSKM', 'Sampling Window (SW)', 'RSKM', and '0.5 x TCCS'. The 'Sampling Window (SW)' is the central block, and the 'RSKM' blocks are positioned on either side of it.</p>

continued...



Date	Version	Changes
July 2014	3.9	<ul style="list-style-type: none"> Added a note in Table 3, Table 4, and Table 5: The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements. Added a note in Table 19: Differential inputs are powered by V_{CCPD} which requires 2.5 V. Updated "Minimum differential eye opening at the receiver serial input pins" specification in Table 20. Updated h2f_user2_clk specification for -C6, -C7, and -I7 speed grades in Table 34. Updated description in "HPS PLL Specifications" section. Updated VCO range maximum specification in Table 35. Updated T_d and T_h specifications in Table 41. Added T_h specification in Table 43 and Figure 10. Updated a note in Figure 17, Figure 18, and Figure 20 as follows: Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required. Removed "Remote update only in AS mode" specification in Table 54. Added DCLK device initialization clock source specification in Table 56. Added description in "Configuration Files" section: The IOCSR .rbf size is specifically for the Configuration via Protocol (CvP) feature. Added "Recommended EPCQ Serial Configuration Device" values in Table 57. Removed $f_{MAX_RU_CLK}$ specification in Table 59.
February 2014	3.8	<ul style="list-style-type: none"> Updated $V_{CCRSTCLK_HPS}$ maximum specification in Table 1. Added $V_{CC_AUX_SHARED}$ specification in Table 1.
December 2013	3.7	<ul style="list-style-type: none"> Updated Table 1, Table 3, Table 19, Table 20, Table 23, Table 25, Table 27, Table 34, Table 44, Table 51, Table 52, Table 55, and Table 61. Removed Preliminary tags for Table 1, Table 2, Table 3, Table 4, Table 5, Table 6, Table 7, Table 9, Table 12, Table 13, Table 14, Table 15, Table 16, Table 17, Table 18, Table 19, Table 20, Table 24, Table 25, Table 26, Table 27, Table 28, Table 32, Table 33, Table 49, Table 50, Table 51, Table 52, Table 53, Table 54, Table 55, Table 57, Table 58, Table 59, Table 60, and Table 62.
November 2013	3.6	Updated Table 23, Table 30, and Table 31.
October 2013	3.5	<ul style="list-style-type: none"> Added "HPS PLL Specifications". Added Table 23, Table 35, and Table 36. Updated Table 1, Table 5, Table 11, Table 19, Table 20, Table 21, Table 22, Table 25, Table 28, Table 34, Table 37, Table 38, Table 39, Table 40, Table 41, Table 42, Table 43, Table 44, Table 45, Table 46, Table 47, and Table 53. Updated Figure 1, Figure 2, Figure 4, Figure 10, Figure 12, Figure 13, and Figure 16. Removed table: GPIO Pulse Width for Cyclone V Devices.

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Date	Version	Changes
June 2013	3.4	<ul style="list-style-type: none"> • Updated Table 20, Table 27, and Table 34. • Updated "UART Interface" and "CAN Interface" sections. • Removed the following tables: <ul style="list-style-type: none"> — Table 45: UART Baud Rate for Cyclone V Devices — Table 47: CAN Pulse Width for Cyclone V Devices
May 2013	3.3	<ul style="list-style-type: none"> • Added Table 33. • Updated Figure 5, Figure 6, Figure 17, Figure 19, and Figure 20. • Updated Table 1, Table 4, Table 5, Table 10, Table 13, Table 19, Table 20, Table 26, Table 32, Table 35, Table 36, Table 43, Table 53, Table 54, Table 57, and Table 61.
March 2013	3.2	<ul style="list-style-type: none"> • Added HPS reset information in the "HPS Specifications" section. • Added Table 57. • Updated Table 1, Table 2, Table 17, Table 20, Table 52, and Table 56. • Updated Figure 18.
January 2013	3.1	Updated Table 4, Table 20, and Table 56.
November 2012	3.0	<ul style="list-style-type: none"> • Updated Table 1, Table 4, Table 5, Table 9, Table 14, Table 16, Table 17, Table 19, Table 20, Table 25, Table 28, Table 52, Table 55, Table 56, and Table 59. • Removed table: Transceiver Block Jitter Specifications for Cyclone V GX Devices. • Added HPS information: <ul style="list-style-type: none"> — Added "HPS Specifications" section. — Added Table 33, Table 34, Table 35, Table 36, Table 37, Table 38, Table 39, Table 40, Table 41, Table 42, Table 43, Table 44, Table 45, and Table 46. — Added Figure 4, Figure 5, Figure 6, Figure 7, Figure 8, Figure 9, Figure 10, Figure 11, Figure 12, Figure 13, Figure 14, Figure 15, and Figure 16. — Updated Table 3.
June 2012	2.0	<p>Updated for the Quartus Prime software v12.0 release:</p> <ul style="list-style-type: none"> • Restructured document. • Removed "Power Consumption" section. • Updated Table 1, Table 3, Table 19, Table 20, Table 25, Table 27, Table 28, Table 30, Table 31, Table 34, Table 36, Table 37, Table 38, Table 39, Table 41, Table 43, and Table 46. • Added Table 22, Table 23, and Table 29. • Added Figure 1 and Figure 2. • Added "Initialization" and "Configuration Files" sections.

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